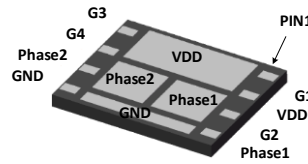
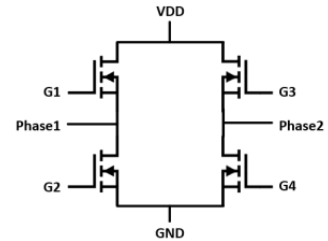


**Main Product Characteristics**

$BV_{DSS}$	30V
$R_{DS(ON)}$	5.5mΩ
$I_D$	64A



DFN5x6



Schematic Diagram

**Features and Benefits**

- Advanced MOSFET process technology
- Ideal for full bridge applications
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



**Description**

The GSMP0364 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

**Absolute Maximum Ratings** ( $T_c=25^{\circ}C$  unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous ( $T_c=25^{\circ}C$ )	$I_D$	64	A
Drain Current-Continuous ( $T_c=100^{\circ}C$ )		40.5	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	256	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	88	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	42	A
Power Dissipation ( $T_c=25^{\circ}C$ )	$P_D$	36.7	W
Power Dissipation-Derate above 25°C		0.29	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.4	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +150	°C
Storage Temperature Range	$T_{STG}$	-55 To +150	°C

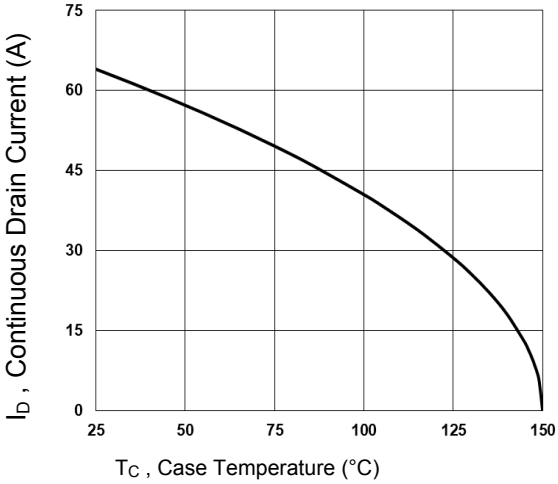
**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^{\circ}\text{C}$ , $I_D=1mA$	-	0.04	-	$V/^{\circ}\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	-	-	1	$\mu A$
		$V_{DS}=24V, V_{GS}=0V, T_J=125^{\circ}\text{C}$	-	-	10	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	4.7	5.5	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	-	6.3	8.5	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	-4	-	mV/ $^{\circ}\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=10A$	-	10	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=15V, I_D=20A,$ $V_{GS}=10V$	-	24.6	49	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	1.85	3.7	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	6.8	13	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=15V, R_G=3.3\Omega,$ $V_{GS}=10V, I_D=15A$	-	7.5	15	nS
Rise Time <sup>3,4</sup>	$t_r$		-	14.5	28	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	35.2	60	
Fall Time <sup>3,4</sup>	$t_f$		-	9.6	19	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V,$ $F=1MHz$	-	1160	1900	pF
Output Capacitance	$C_{oss}$		-	200	400	
Reverse Transfer Capacitance	$C_{rss}$		-	180	360	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	2.5	5.0	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_s$	$V_G=V_D=0V, \text{Force Current}$	-	-	64	A
Pulsed Source Current <sup>3</sup>	$I_{SM}$		-	-	128	A
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS}=0V, I_s=1A, T_J=25^{\circ}\text{C}$	-	-	1	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_s=10A,$ $di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	-	115	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	148	-	nC

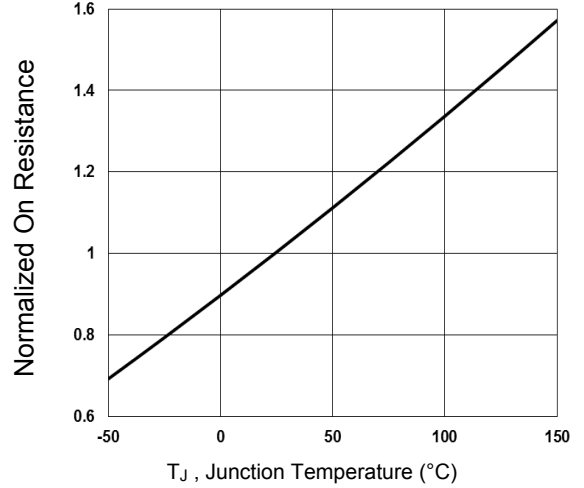
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=42A, R_G=25\Omega$ , starting  $T_J=25^{\circ}\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operation temperature.

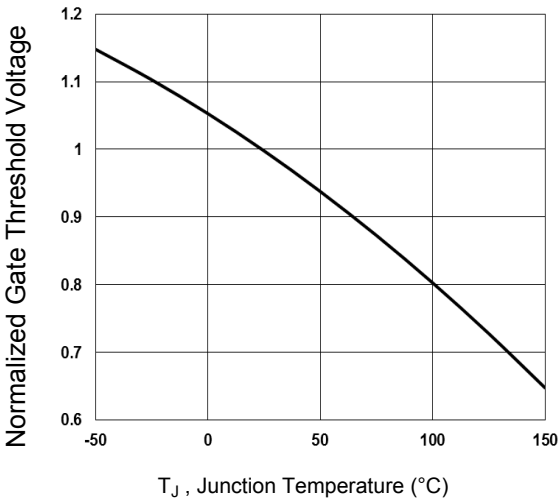
**Typical Electrical and Thermal Characteristic Curves**



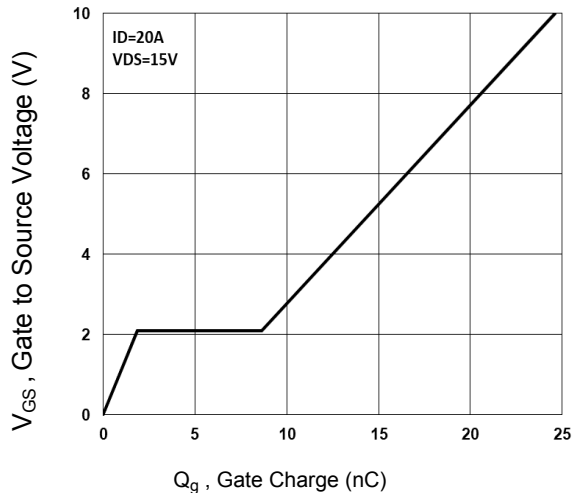
**Fig.1 Continuous Drain Current vs. Tc**



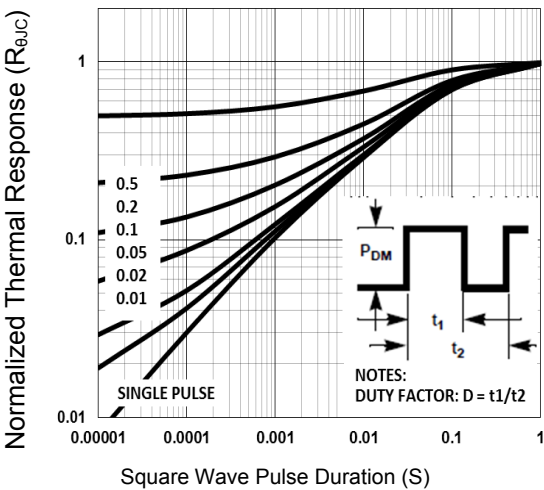
**Fig.2 Normalized  $R_{DS(ON)}$  vs.  $T_J$**



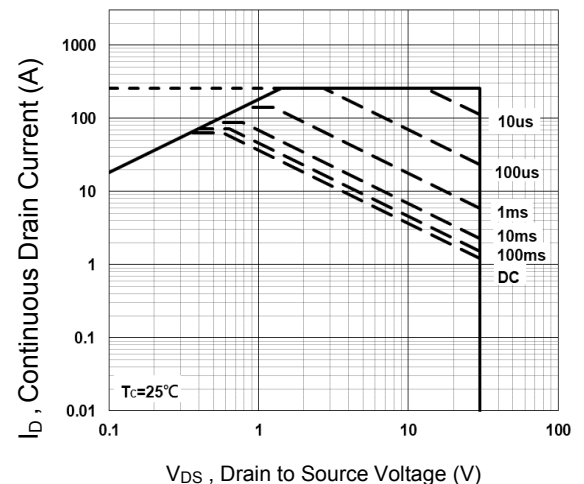
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.4 Gate Charge Waveform**



**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristic Curves**

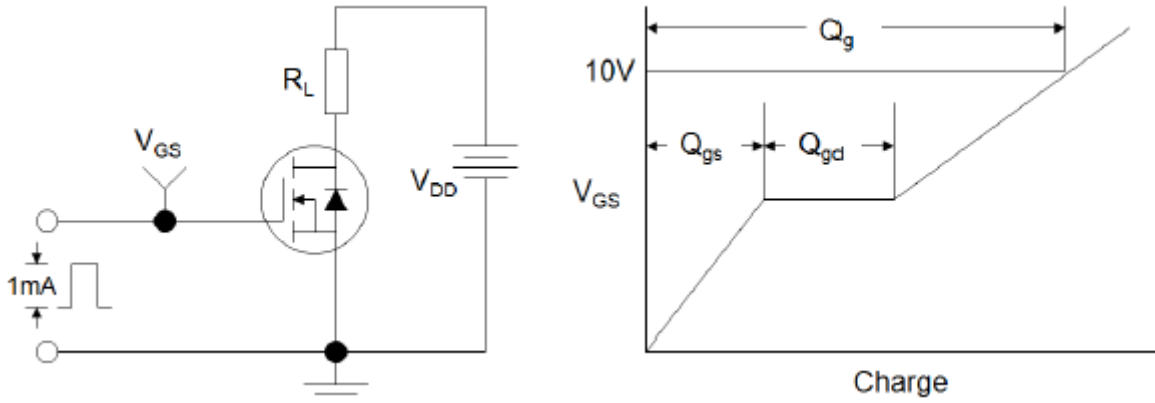


Figure 7. Gate Charge Test Circuit & Waveform

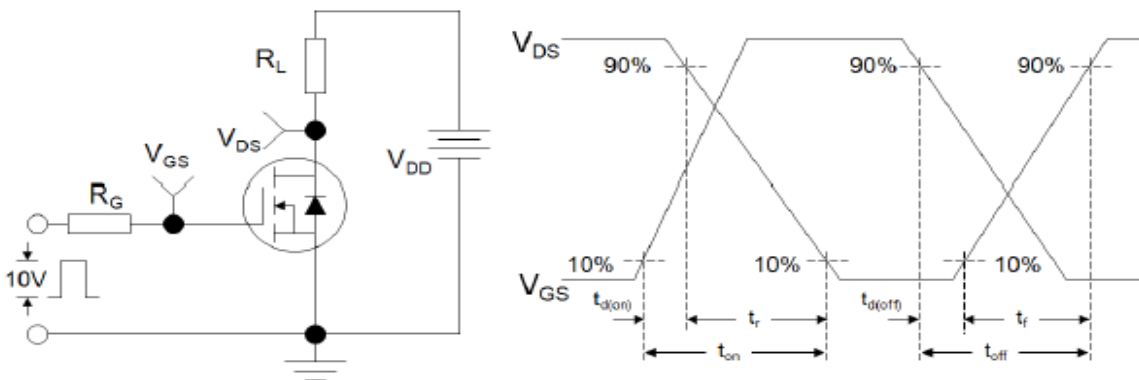


Figure 8. Resistive Switching Test Circuit & Waveforms

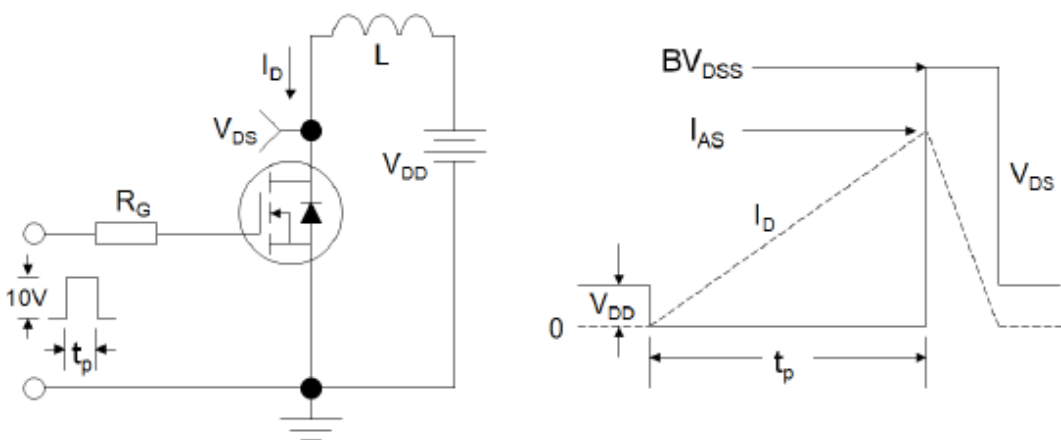
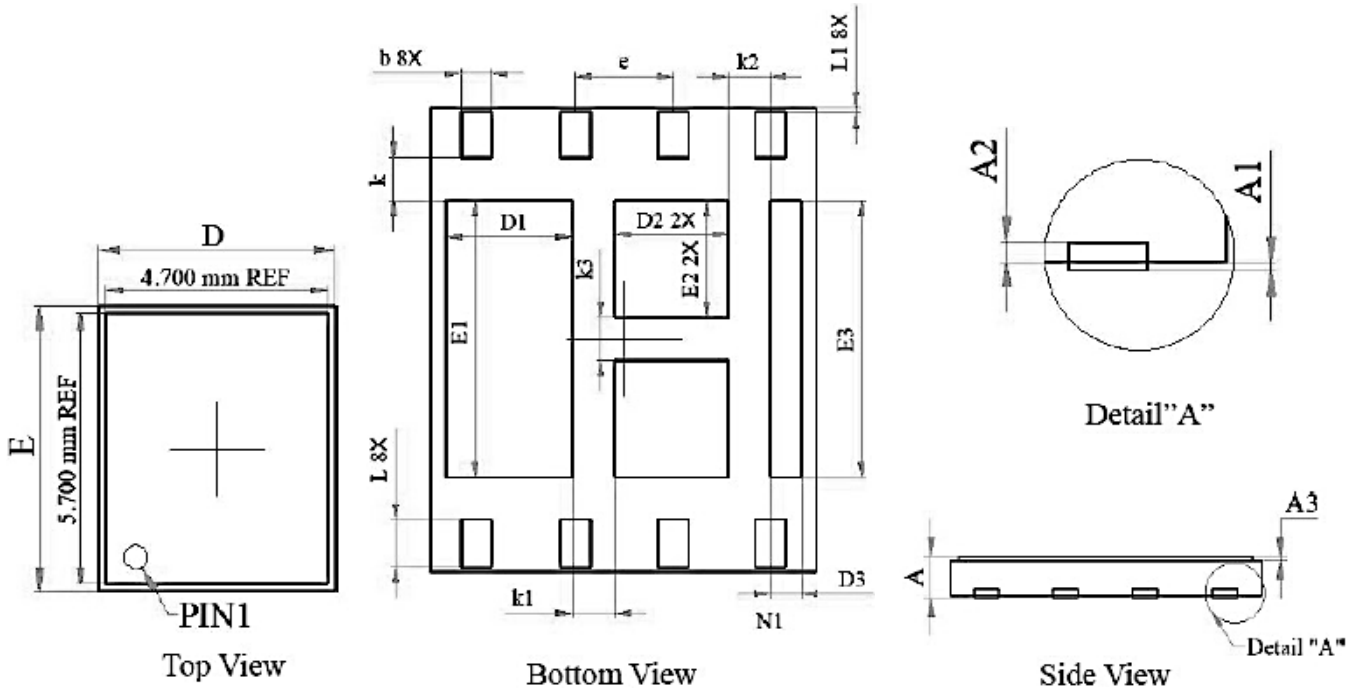


Figure 9.  $E_{AS}$  Circuit & Waveforms

**Package Outline Dimensions**

**DFN5x6**



Symbol	Dimensions In Millimeters			Symbol	Dimensions In Millimeters		
	MIN	Normal	MAX		MIN	Normal	MAX
A	0.530	-	0.600	D3	0.300	0.400	0.500
A1	-	-	0.005	E3	3.500	3.600	3.700
A2	0.030	-	0.100	b	0.350	0.400	0.450
A3	0.050	-	0.100	L	0.550	0.600	0.650
D	4.900	5.000	5.100	L1	0.010	0.050	0.090
E	5.900	6.000	6.100	k	0.550 REF		
D1	1.525	1.625	1.725	k1	0.550 REF		
E1	3.500	3.600	3.700	k2	0.550 REF		
D2	1.375	1.475	1.575	k3	0.550 REF		
E2	1.425	1.525	1.625	e	1.27 BSC		

**Recommended Pad Layout** (Unit in MM)

